



AWAD 2017



2017 Asia-Pacific Workshop on Fundamentals and Applications of Advanced Semiconductor Devices

<http://awad2017.ieieweb.org>

July 3 – 5, 2017

Hotel Hyundai (Gyeongju), Gyeongju-si, Korea

First Call for Papers

2017 Asia-Pacific Workshop on Fundamentals and Applications of Advanced Semiconductor Devices (AWAD 2017) will be held at Hotel Hyundai (Gyeongju), Gyeongju-si, Korea, from July 3 (Mon.) to 5 (Wed.), 2017. This annual workshop has been held alternately in Japan and Korea since 1993, and the 2017 Workshop will be the 25th in a series of the workshops. The purposes of this workshop are to bring scientists and engineers together, actively engaged in advanced semiconductor devices and materials, and to discuss the present and future device processing and related technologies. The workshop will cover the entire field of semiconductor devices and materials, from fundamental physics to recent improvements in device performance and processing technology.

Topics to be discussed will include, but not necessarily be limited to, the following areas:

- Advanced integration technologies
- ULSI process and technologies
- High-speed devices and circuits
- High power devices
- Wide bandgap materials and devices
- Novel devices and circuits
- Optoelectronic devices and applications
- MOS/bipolar devices and technologies
- Compound semiconductor materials and devices
- Microwave/Millimeter-wave devices and circuits
- TFT materials, devices and circuits
- Quantum effect/single electron devices
- Sensors and displays
- Nano, 2D materials, NEMS/MEMS, wearable devices, etc.

Sponsored by

The Institute of Electronics and Information Engineers (IEIE), in cooperation with Electronics Society, The Institute of Electronics, Information and Communication Engineers of Japan (IEICE-ES)

Paper submission

Abstract deadline: March 31st (Fri.), 2017

Prospective authors should submit the title, author's name(s), affiliation(s), e-mail address, and 100 words abstract on the conference website (<http://awad2017.ieieweb.org>) no later than March 31st (Fri.), 2017.

For any questions from Korea and other countries, ask:

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Technical Digest

The authors of the accepted abstracts will be asked to submit camera-ready manuscripts (2 - 6 pages including figures) for the technical digest which will be distributed to participants at the workshop. The details will directly be notified to the authors of accepted papers. The deadline of the manuscript is May 26th (Fri.), 2017. The full paper template is available for download at the conference website.

Special issues in Journal of Semiconductor Technology and Science (JSTS) / IEICE Transaction on Electronics (IEICE-C)

Authors are encouraged to submit their extended manuscripts to the special issue either in 'Journal of Semiconductor Technology and Science' or 'IEICE Transactions on Electronics' (SCIE journals). The submitted papers will be peer-reviewed and upon acceptance published in April 2018 (JSTS) and May 2018 (IEICE-C). Detailed information will be accounted at the workshop and conference website.

Venue & Accommodation

For detailed information, visit the conference homepage: <http://awad2017.ieieweb.org>

Social Events

Banquet is scheduled in the evening of July 4th (Tue.).

Language

The official language of the workshop is English.

Registration

	Regular	Student
Pre-registration Fee	₩300,000	₩120,000
On-site Registration Fee	₩350,000	₩150,000

*The conference receives cash (KRW only) or credit card on conference site for registration fee.

*For pre-registration, you can send a pre-registration form by email and pay at the site.

*Bank transfer is only available for domestic pre-registration.

*Banquet is included in the registration fee.

*The deadline for the pre-registration is June 16, 2017.

Important Dates:

March 31 (Fri.), 2017: Deadline for abstract submission
May 26 (Fri.), 2017: Deadline for camera-ready manuscript

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